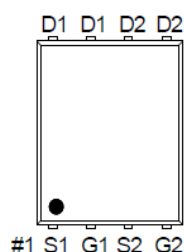


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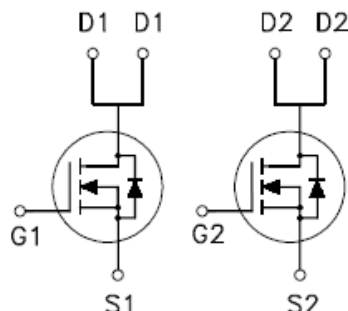
PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
20V	5.7mΩ @ $V_{GS} = 4.5V$	56A



PDFN 5*6P

G. GATE
D. DRAIN
S. SOURCE



ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	20	V
Gate-Source Voltage		V_{GS}	±8	
Continuous Drain Current ³	$T_C = 25\text{ }^{\circ}\text{C}$	I_D	56	A
	$T_C = 100\text{ }^{\circ}\text{C}$		36	
Pulsed Drain Current ¹		I_{DM}	70	
Continuous Drain Current	$T_A = 25\text{ }^{\circ}\text{C}$	I_D	17	
	$T_A = 70\text{ }^{\circ}\text{C}$		14	
Avalanche Current		I_{AS}	40	mJ
Avalanche Energy		E_{AS}	79	
Power Dissipation	$T_C = 25\text{ }^{\circ}\text{C}$	P_D	31	W
	$T_C = 100\text{ }^{\circ}\text{C}$		12.5	
Power Dissipation	$T_A = 25\text{ }^{\circ}\text{C}$	P_D	2.9	
	$T_A = 70\text{ }^{\circ}\text{C}$		1.8	
Operating Junction & Storage Temperature Range		T_J, T_{STG}	-55 to 150	$^{\circ}\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		4	$^{\circ}\text{C} / \text{W}$
Junction-to-Ambient ²	$R_{\theta JA}$		43	

¹Pulse width limited by maximum junction temperature.

²The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^{\circ}\text{C}$.

³Package limitation current is 22A.

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ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	20			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.3	0.7	1	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 8V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 16V, V_{GS} = 0V,$			1	μA
		$V_{DS} = 10V, V_{GS} = 0V, T_J = 70^\circ C$			10	
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 17A$		4.4	5.7	m Ω
		$V_{GS} = 2.5V, I_D = 17A$		4.9	6.2	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 17A$		100		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 10V, f = 1MHz$		4120		pF
Output Capacitance	C_{oss}			481		
Reverse Transfer Capacitance	C_{rss}			409		
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$		1		Ω
Total Gate Charge ²	Q_g	$V_{GS}=2.5V$		28.8		nC
		$V_{GS}=4.5V$		48.2		
Gate-Source Charge ²	Q_{gs}	$V_{DS} = 10V, I_D = 17A$		6		
Gate-Drain Charge ²	Q_{gd}			14		
Turn-On Delay Time ²	$t_{d(on)}$			20		
Rise Time ²	t_r	$V_{DS} = 10V, I_D \cong 17A,$ $V_{GS}= 4.5V, R_{GEN} = 6\Omega$		25		
Turn-Off Delay Time ²	$t_{d(off)}$			180		
Fall Time ²	t_f			85		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)						
Continuous Current ³	I_S				24	A
Forward Voltage ¹	V_{SD}	$I_F = 17A, V_{GS} = 0V$			1.3	V
Reverse Recovery Time	t_{rr}	$I_F = 17A, dI_F/dt = 100A/\mu S$		25		nS
Reverse Recovery Charge	Q_{rr}			14		nC

¹Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.

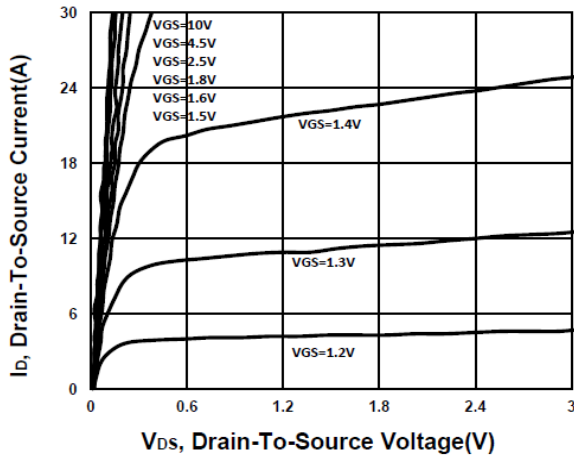
²Independent of operating temperature.

³Package limitation current is 22A.

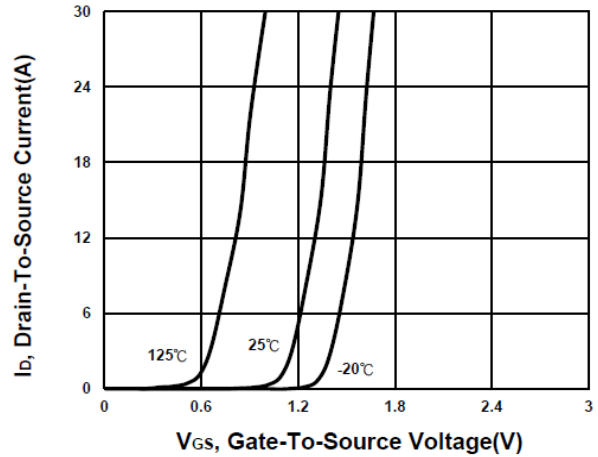
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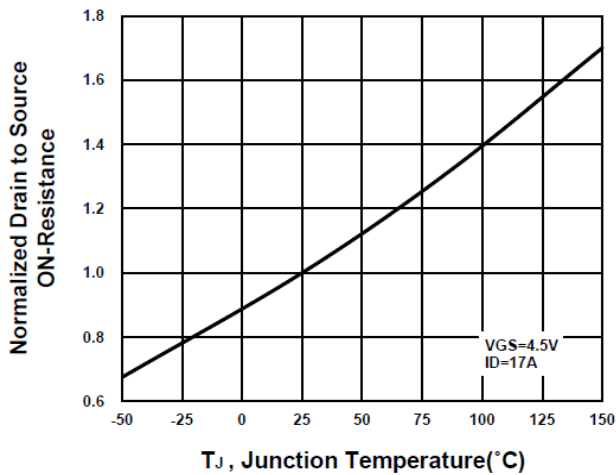
Output Characteristics



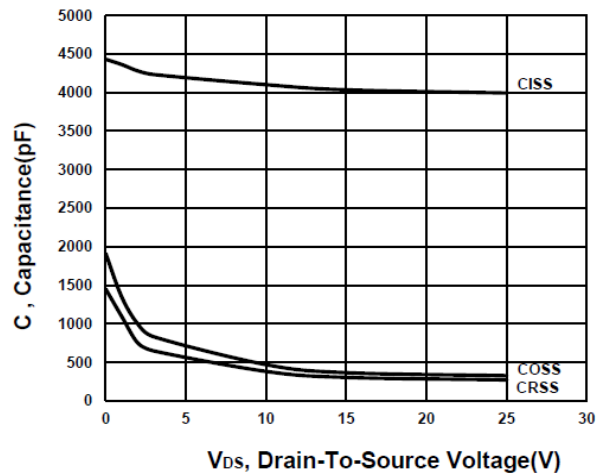
Transfer Characteristics



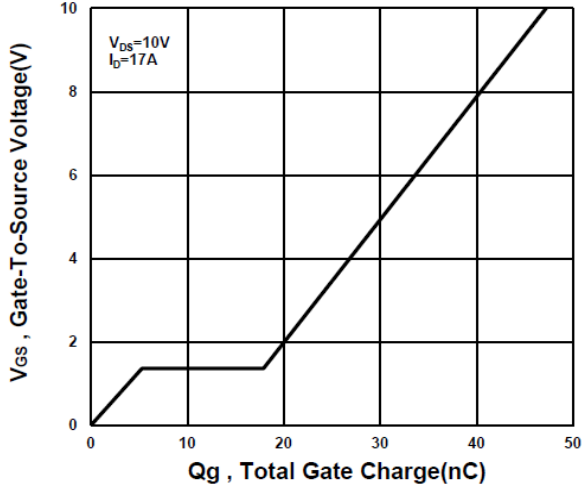
On-Resistance VS Temperature



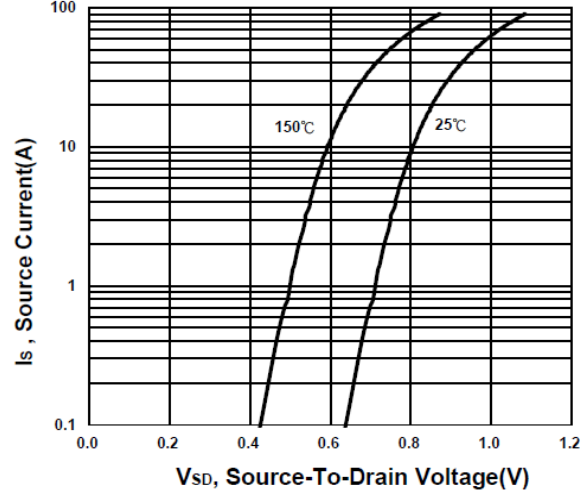
Capacitance Characteristic



Gate charge Characteristics



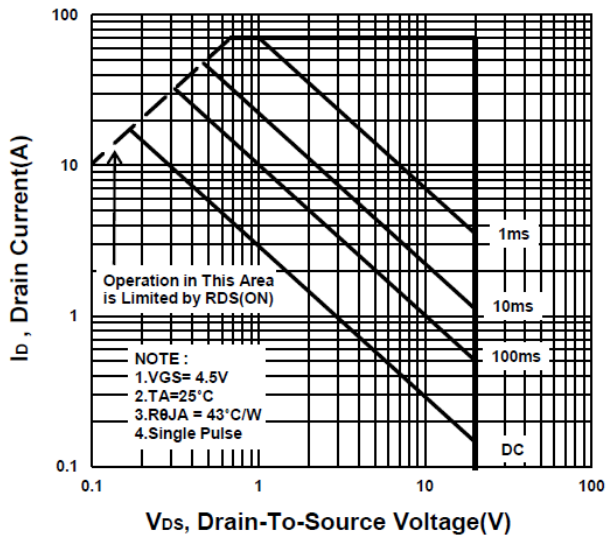
Source-Drain Diode Forward Voltage



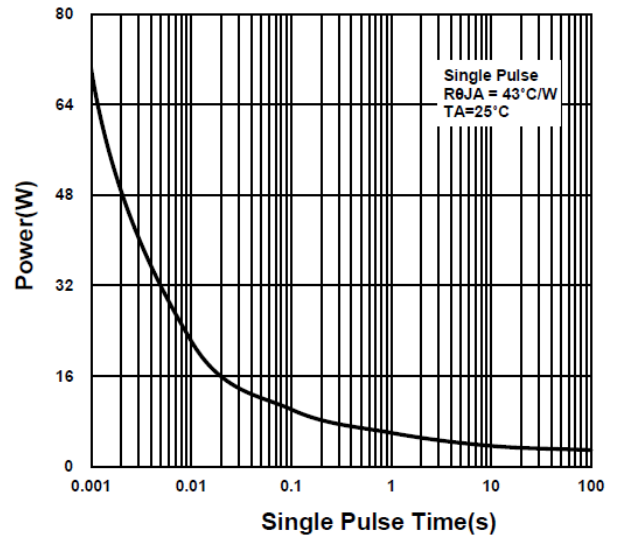
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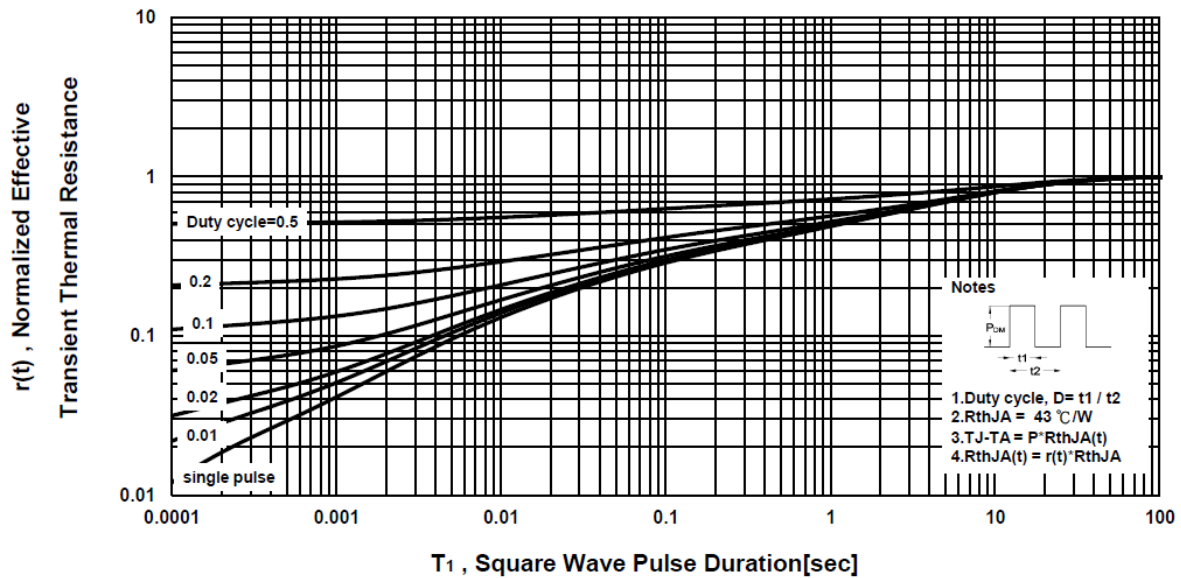
Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve



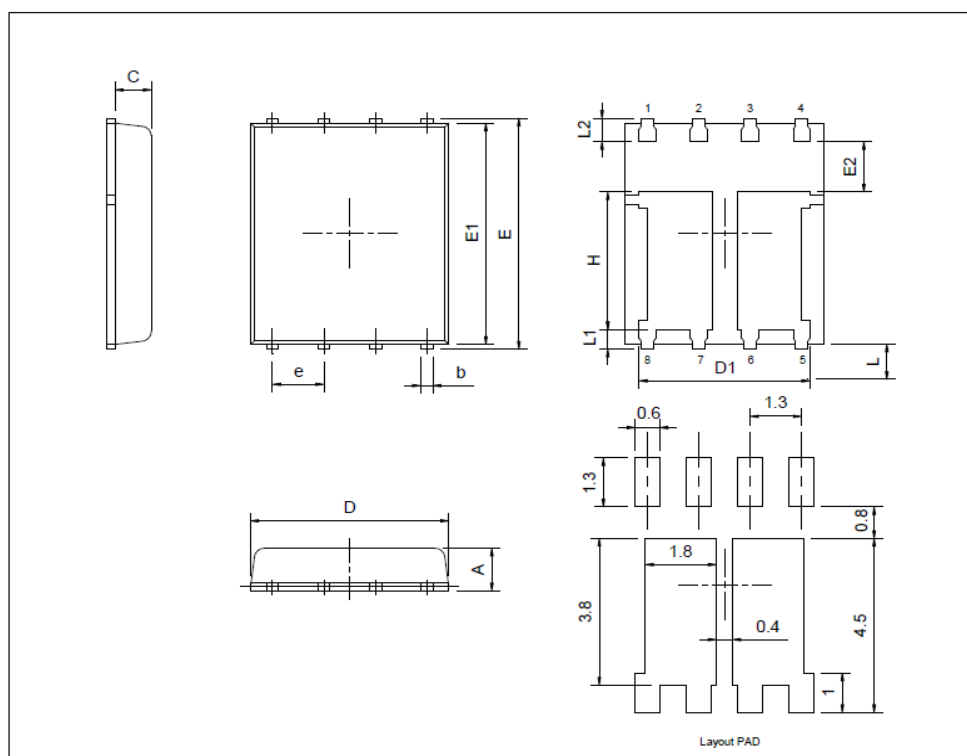
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Package Dimension

PDFN 5x6P(左右 Dual) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	0.9		1.17	L	0.05		0.25
b	0.33		0.51	L1	0.38		0.61
C	0.7		0.97	L2	0.38		0.71
D	4.8		5.0	H	3.38		3.78
D1	3.61		4.31				
E	5.9		6.15				
E1	5.65		5.85				
E2	1.1						
e		1.27					



*散热片形状会因为封装厂框架不同而有所差异。